

Initial Product/Process Change Notification

Document #:IPCN23658ZA Issue Date:03 Dec 2020

Title of Change:	Wafer fab transfer to ON Semiconductor Gresham, Oregon USA from ON Semiconductor Fab2, Oudenaarde, Belgium related to Fab2 sale	
Proposed Changed Material First Ship Date:	d Material First Ship 24 Jun 2022 or earlier if approved by customer	
Current Material Last Order Date:	Jun 30, 2021 with flexibility for update at FPCN issue date	
Current Material Last Delivery Date:	12months after FPCN issue date, unless otherwise mutually agreed	
Product Category:	Active components – Integrated circuits	
Contact information:	Contact your local ON Semiconductor Sales Office or Alicia.Tuckett@onsemi.com	
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office to place sample order or <pcn.samples@onsemi.com>. Sample requests are to be submitted no later than 45 days after publication of this change notification. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.</pcn.samples@onsemi.com>	
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or Catherine.DeKeukeleire@onsemi.com	
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 12 months prior to implementation of the change. In case of questions, contact < PCN. Support@onsemi.com>.	
Change Category		
Category	Type of Change	
Process - Wafer Production	Move of all or part of wafer fab to a different location/site/subcontractor Change of gate material / dielectrics, New wafer diameter	

Description and Purpose:

Wafer fab transfer to ON Semiconductor Gresham, Oregon USA from ON Semiconductor Fab2, Oudenaarde, Belguim due to Fab2 sale.

NCV891334MW33R2G was discontinued, but was later decided to continue with this part with the change per IPCN23658ZA.

PD23406ZA: NCV891334MW33R2G (IPCN23658ZA will cancel and replace PD23406ZA)

Wafer fab location	Fab2, Oudenaarde, Belgium (Current Fab)	ON Gresham, Oregon, USA (New Fab)
Wafer Diameter	Substrate: Si (150mm) 6"	Substrate: Si (200mm) 8"

	Product marking change	Documented at product level at FPCN issue
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Reason / Motivation for Change:	Source/Supply/Capacity Changes
Anticipated impact on fit, form, function, reliability, product safety or manufacturability:	No anticipated impacts.

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Sites Affected:				
ON Semiconductor Sites	External Foundry/Subcon Sites			
ON Semiconductor Gresham, Oregon	None			
ON Semiconductor Oudenaarde, Belgium				

Marking of Parts/ Traceability of Change:

Traceability guaranteed by datecode

Reliability Data Summary:

Qualification plan is device specific and will be provided upon request

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Current Part Number	New Part Number	Qualification Vehicle
NCV885201D1R2G	NCV885201D1R2G	NA
NCV887103D1R2G	NCV887103D1R2G	NA
NCV887601D1R2G	NCV887601D1R2G	NA
NCV887701D1R2G	NCV887701D1R2G	NA
NCV887720D1R2G	NCV887720D1R2G	NA
NCV890204MWR2G	NCV890204MWR2G	NA
NCV891334MW33R2G	NCV891334MW33R2G	NA
NCV86601BDT50RKG	NCV8760CDT501RKG	NA

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